



Material Content Data Sheet



Halogen-Free

Sales Product Name	IFX24401TE V50	Issued	24. February 2022
MA#	MA005699816		
Package	PG-TO252-5-11	Weight*	356.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.671	0.47	0.47	4687	4687
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		574	
	non noble metal	copper	7440-50-8	204.243	57.28	57.36	572791	573537
wire	non noble metal	aluminium	7429-90-5	0.186	0.05	0.05	520	520
encapsulation	inorganic material	zinc oxide	1314-13-2	1.417	0.40		3974	
	miscellaneous	miscellaneous	-	7.085	1.99		19869	
	plastics	epoxy resin	-	21.254	5.96		59607	
	inorganic material	silicon dioxide	60676-86-0	111.940	31.39	39.74	313932	397382
lead finish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14226	14226
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	214	215
solder	non noble metal	tin	7440-31-5	0.067	0.02		189	
	noble metal	silver	7440-22-4	0.084	0.02		236	
	non noble metal	lead	7439-92-1	3.212	0.90	0.94	9008	9433
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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